

FIG. 1

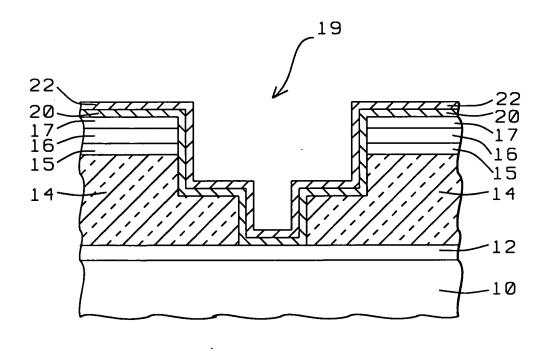


FIG. 2

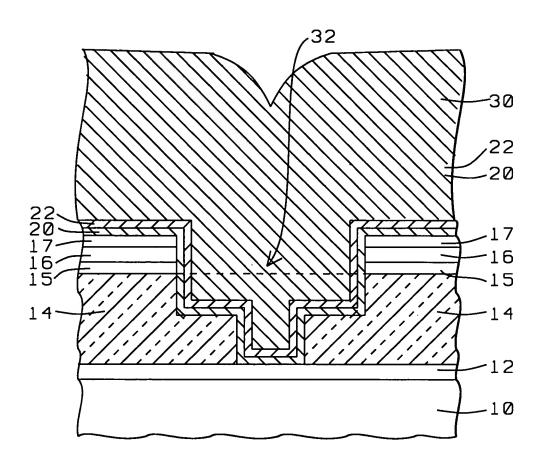
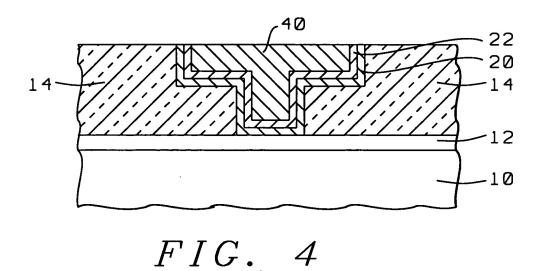
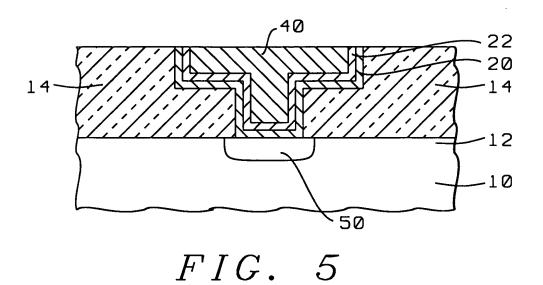
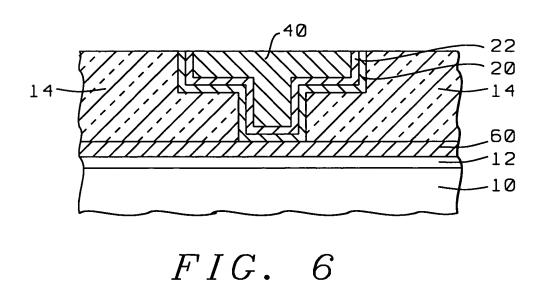


FIG. 3







COMPARISON OF SOFT AND HARD INTE	ERFACE LAYE	ER FOR low-	ARD INTERFACE LAYER FOR low-k DAMASCENE Cu CMP
DAMASCENE FILM STACK	DISH/ RANGE(A)	EROSION/ RANGE(A)	COMMENT
SILK SKA/PEOX 1KA/SiON 600A	311/199	499/321	low k + SOFI FILM+DARC
SILK SKA/PE-TEOS 1KA/SiON 600A	211/232	236/343	low k + SOFT FILM+DARC
SILK SKA/SIN 1KA/SiON 600A	749/591	645/543	low k + HARD FILM+DARC
SILK 5KA/PEOX 500A+SIN500A/SiON 600A 659/588	659/588	595/424	low k + SOFT&HARD FILM+DARC
SILK 5KA/SIN500A+PEOX 500A/S10N 600A 681/594	681/594	587/478	587/478 10w k + HARD&SOFT FILM+DARC

FIG. 7

COMPARISON OF SOFT AND HARD INTERFACE LAYER FOR low-k DAMASCENE CU CMP
SOME DEFECT SPOTS
SOME DEFECT SPOTS
NO DAMAGE AND DEFECT 10W K + HARD FILM+DARC
SILK SKA/PEOX 500A+SIN500A/SiON 600A NO DAMAGE AND DEFECT 10W K + SOFT&HARD FILM+DARC
SILK SKA/SINSØØA+PEOX SØØA/SiON 600A NO DAMAGE AND DEFECT 10W K + HARD&SOFT FILM+DARC

FIG. 8